

Assignment 01

Exercise 1:

1. Our favorite program runs in 10 seconds on computer A, which has a 2 GHz clock. We are trying to help a computer designer build a computer, B, which will run this program in 6 seconds. The designer has determined that a substantial increase in the clock rate is possible, but this increase will affect the rest of the CPU design, causing computer B to require 1.2 times as many clock cycles as computer A for this program. What clock rate should we tell the designer to target?
2. Suppose we have two implementations of the same instruction set architecture. Computer A has a clock cycle time of 250 ps and a CPI of 2.0 for some programs, and computer B has a clock cycle time of 500 ps and a CPI of 1.2 for the same program. Which computer is faster for this program and by how much?
3. A compiler designer is trying to decide between two code sequences for a computer. The hardware designers have supplied the following facts:

	A	B	C
CPI	1	2	3

Table 1.1: CPI for each instruction class

For a particular high-level language statement, the compiler writer is considering two code sequences that require the following instruction counts:

Code sequence	A	B	C
1	2	1	2
2	4	1	1

Table 1.2: Instruction counts for each instruction class

Which code sequence executes the most instructions? Which will be faster? What is the CPI for each sequence?

4. A given application written in Java runs 15 seconds on a desktop processor. A new Java compiler is released that requires only 0.6 as many instructions as the old compiler. Unfortun-

nately, it increases the CPI by 1.1. How fast can we expect the application to run using this new compiler? Pick the right answer from the three choices below:

a.

$$\frac{15 \times 0.6}{1.1} = 8.2sec \quad (1.1)$$

b.

$$15 \times 0.6 \times 1.1 = 9.9sec \quad (1.2)$$

c.

$$\frac{15 \times 1.1}{0.6} = 27.5sec \quad (1.3)$$

5. How do you measure fastest? Consider the three different processors P1, P2, and P3 executing the same instruction set. P1 has a clock cycle time of 0.33 ns and CPI of 1.5; P2 has a clock cycle time of 0.40 ns and CPI of 1.0; P3 has a clock cycle time of 0.25 ns and CPI of 2.2.
- Which has the highest clock rate? What is it?
 - Which is the fastest computer? If the answer is different than above, explain why. Which is the slowest?
 - How do the answers for a and b reflect the importance of benchmarks?

Exercise 2:

Consider three different processors, P1, P2, and P3, executing the same instruction set. P1 has a 3 GHz clock rate and a CPI of 1.5. P2 has a 2.5 GHz clock rate and a CPI of 1.0. P3 has a 4.0 GHz clock rate and a CPI of 2.2.

- Which processor has the highest performance expressed in instructions per second?
- If the processors execute a program in 10 seconds, find the number of cycles and the number of instructions.
- We are trying to reduce the execution time by 30%, but this leads to an increase of 20% in the CPI. What clock rate should we have to get this time reduction?

Exercise 3:

Consider two different implementations of the same instruction set architecture. The instructions can be divided into four classes according to their CPI (classes A, B, C, and D). P1 with a clock rate of 2.5 GHz and CPIs of 1, 2, 3, and 3, and P2 with a clock rate of 3 GHz and CPIs of 2, 2, 2, and 2.

Given a program with a dynamic instruction count of 1.0E6 instructions divided into classes as follows: 10% class A, 20% class B, 50% class C, and 20% class D, which is faster: P1 or P2?

- What is the global CPI for each implementation?
- Find the clock cycles required in both cases.

Exercise 4:

Assume a 15 cm diameter wafer has a cost of 12, contains 84 dies, and has 0.020 defects/cm². Assume a 20 cm diameter wafer has a cost of 15, contains 100 dies, and has 0.031 defects/cm².

- Find the yield for both wafers.
- Find the cost per die for both wafers.
- If the number of dies per wafer is increased by 10% and the defects per area unit increases by 15%, find the die area and yield.
- Assume a fabrication process improves the yield from 0.92 to 0.95. Find the defects per area unit for each version of the technology given a die area of 200 mm².